

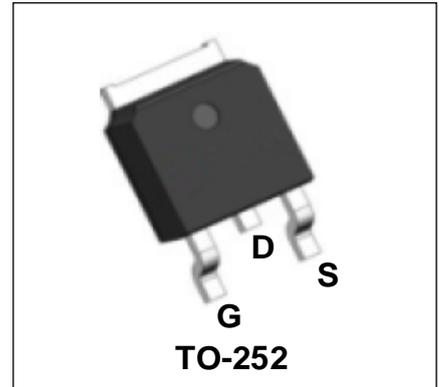
20V N-Channel Enhancement Mode Power MOSFET

Description

WMO90N02T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

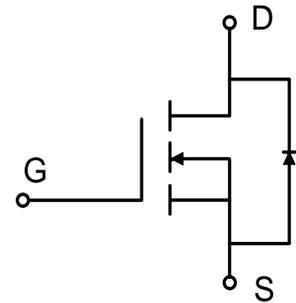
Features

- $V_{DS} = 20V$, $I_D = 90A$
 $R_{DS(on)} < 4.5m\Omega @ V_{GS} = 4.5V$
 $R_{DS(on)} < 5m\Omega @ V_{GS} = 2.5V$
- Low $R_{DS(on)}$
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



Applications

- High Current Load Applications
- Load Switching
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current ¹	I_D	$T_C = 25^\circ C$	90
		$T_C = 100^\circ C$	62
Pulsed Drain Current ²	I_{DM}	222	A
Single Pulse Avalanche Energy ³	EAS	101.2	mJ
Avalanche Current	I_{AS}	45	A
Total Power Dissipation ⁴	P_D	39	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to- Ambient ¹	$R_{\theta JA}$	35	$^\circ C/W$
Thermal Resistance from Junction-to-Case ¹	$R_{\theta JC}$	3.2	$^\circ C/W$

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 10V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	-	-	1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.4	0.65	1	V
Drain-Source on-Resistance ²	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 30A$	-	3.2	4.5	m Ω
		$V_{GS} = 2.5V, I_D = 20A$	-	3.9	5	
		$V_{GS} = 1.8V, I_D = 10A$	-	5.3	7.5	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$	-	3850	-	pF
Output Capacitance	C_{oss}		-	490	-	
Reverse Transfer Capacitance	C_{rss}		-	440	-	
Switching Characteristics						
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	-	1.8	-	Ω
Total Gate Charge	Q_g	$V_{GS} = 4.5V, V_{DS} = 10V, I_D = 15A$	-	100	-	nC
Gate-Source Charge	Q_{gs}		-	24	-	
Gate-Drain Charge	Q_{gd}		-	20	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 4.5V, V_{DS} = 10V, R_G = 3\Omega, R_L = 1\Omega, I_D = 10A$	-	11.5	-	nS
Rise Time	t_r		-	24.5	-	
Turn-off Delay Time	$t_{d(off)}$		-	33.2	-	
Fall Time	t_f		-	9.6	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current ^{1,5}	I_S	$V_G = V_D = 0V$, Force Current	-	-	90	A
Body Diode Reverse Recovery Time	t_{rr}	$V_R = 10V, I_F = 15A, di/dt = 100A/\mu s$	-	36	-	nS
Body Diode Reverse Recovery Charge	Q_{rr}		-	40	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=15V, V_{GS}=10V, L=0.1mH, I_{AS}=45A$
- 4.The power dissipation is limited by 175 $^\circ\text{C}$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

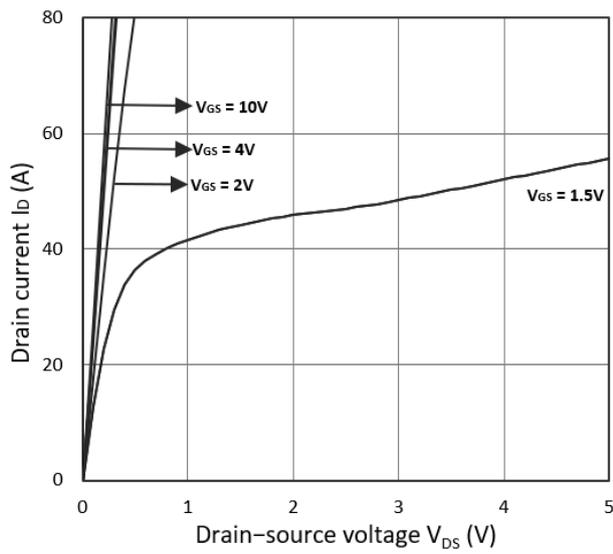


Figure 1. Output Characteristics

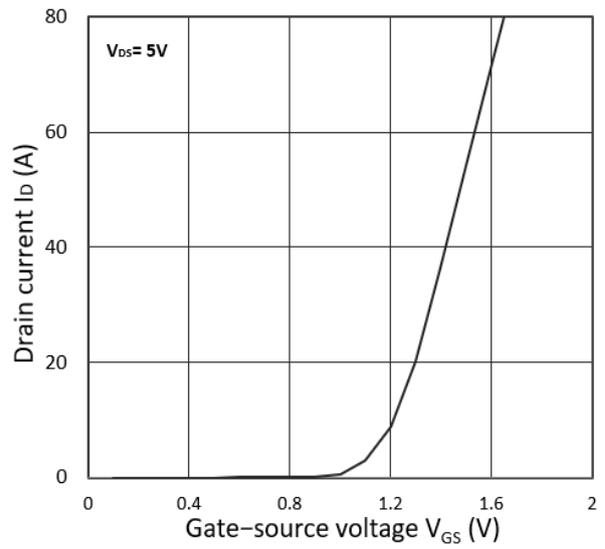


Figure 2. Transfer Characteristics

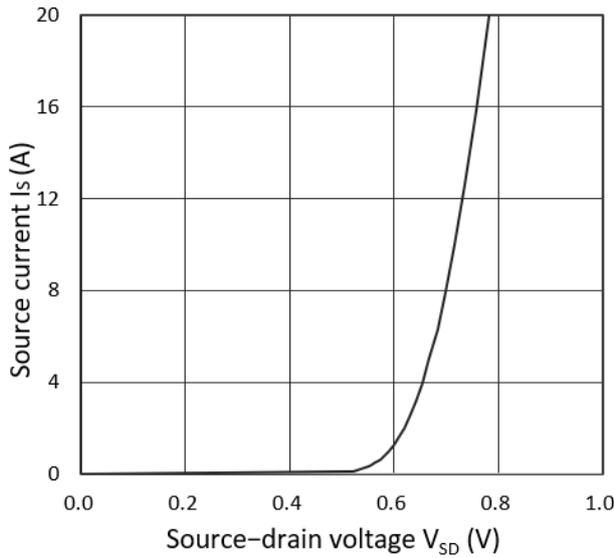


Figure 3. Forward Characteristics of Reverse

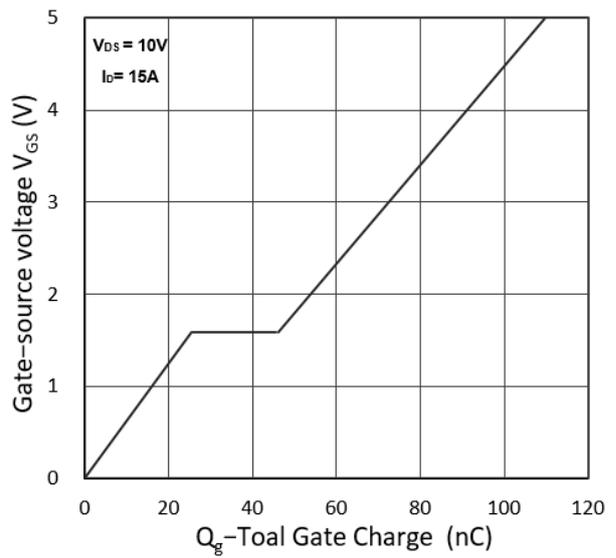


Figure 4. Gate Charge Characteristics

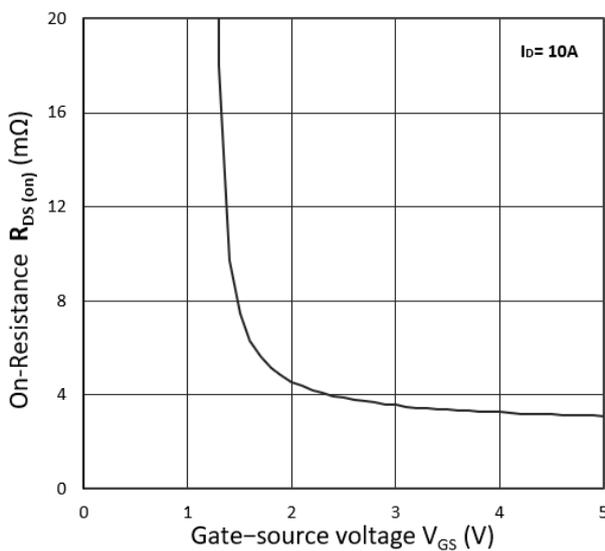


Figure 5. $R_{DS(on)}$ vs. V_{GS}

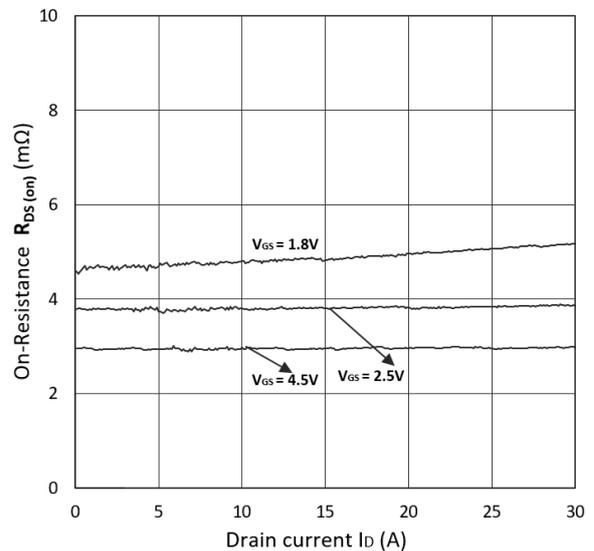


Figure 6. $R_{DS(on)}$ vs. I_D

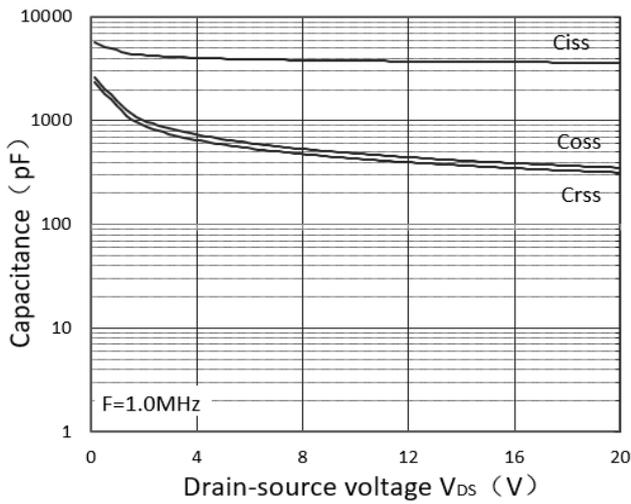


Figure 7. Capacitance Characteristics

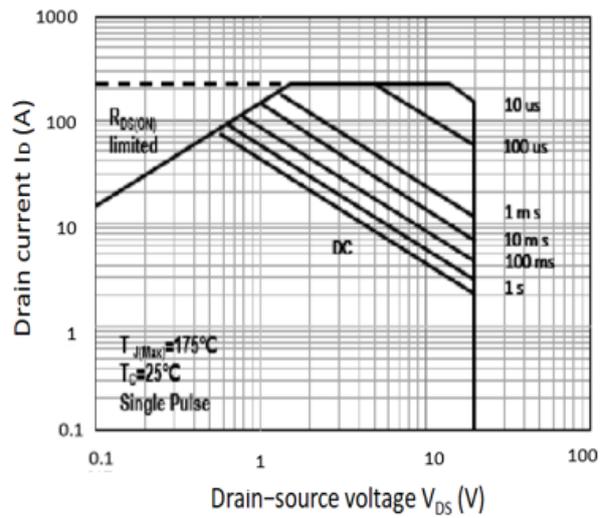


Figure 8. Safe Operating Area

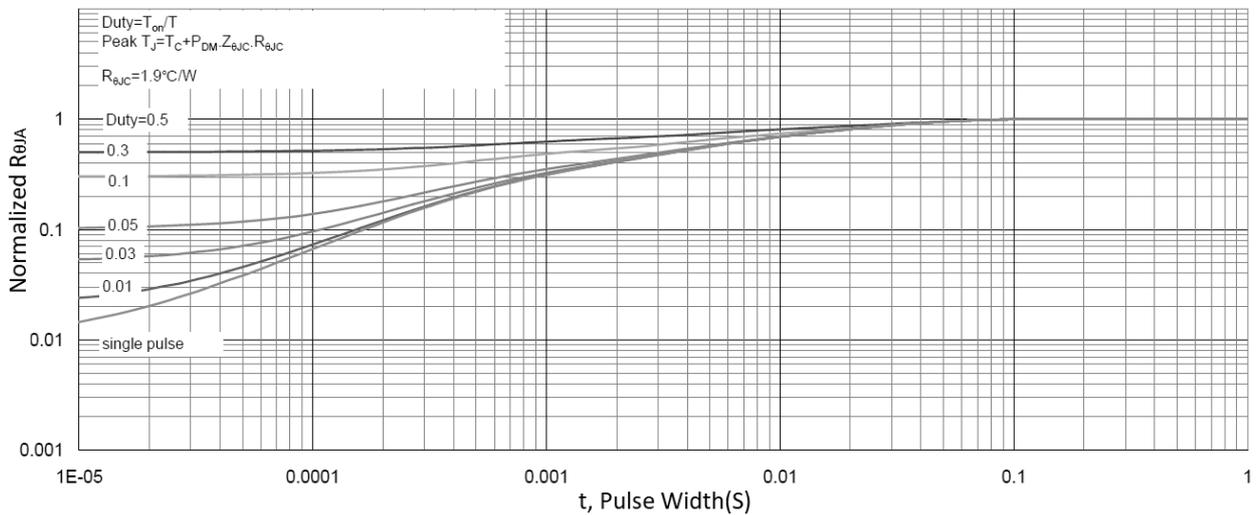


Figure 9. Normalized Maximum Transient Thermal Impedance

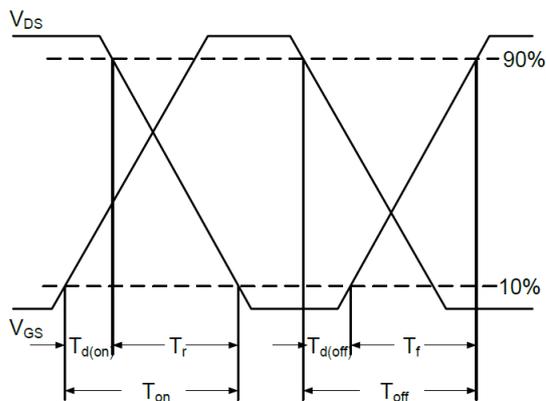


Figure 10. Switching Time Waveform

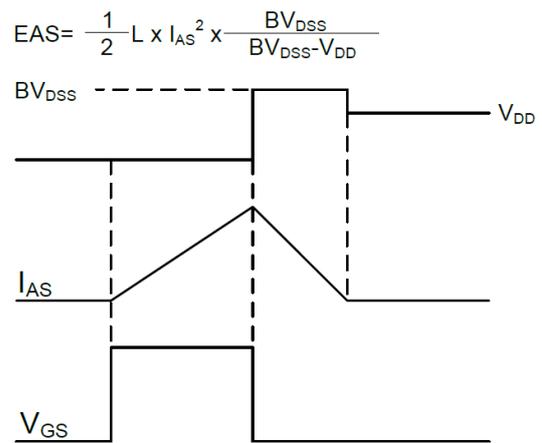
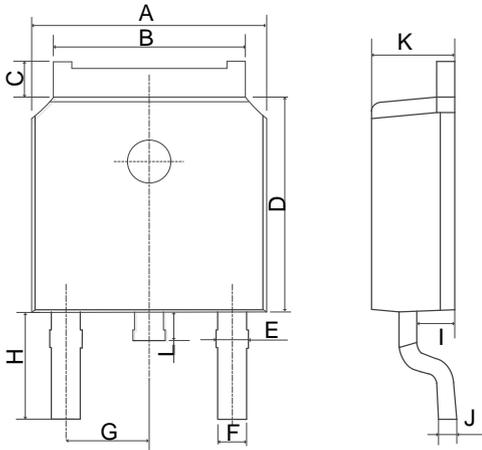


Figure 11. Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Mechanical Dimensions for TO-252

COMMON DIMENSIONS

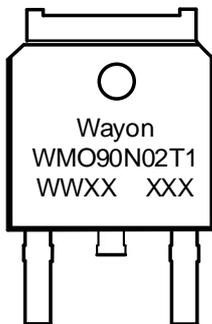


SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
E	0.68	1.10
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00

Ordering Information

Part	Package	Marking	Packing method
WMO90N02T1	TO-252	WMO90N02T1	Tape and Reel

Marking Information



WMO90N02T1 = Device code
 WWXX XXX= Date code

Contact Information

No.1001, Shiwan(7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-50310888 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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